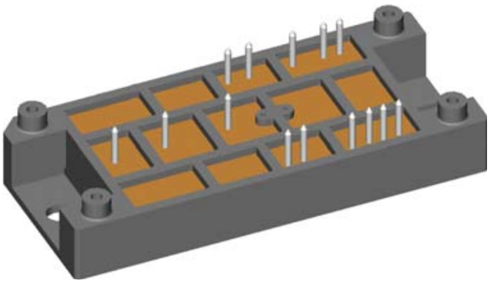
Standard Rectifier Module

3~ Rectifier			Brake Chopper		
V_{RRM}	=	1600 V	V_{CES}	=	1200 V
I_{DAV}	=	180 A	I_{C25}	=	155 A
I_{FSM}	=	1100 A	$V_{CE(sat)}$	=	2.05 V

3~ Rectifier Bridge + Brake Unit

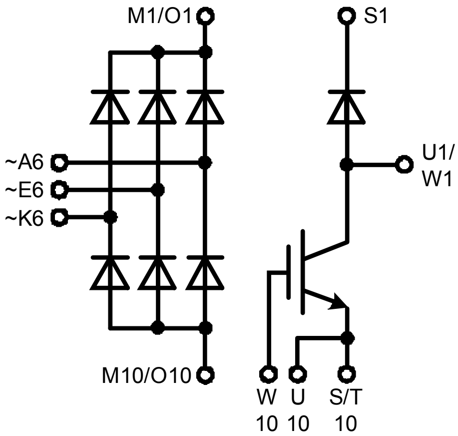
Part number

VUB120-16NOX



Backside: isolated

E72873



Features / Advantages:

- Package with DCB ceramic base plate
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: V2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			1700	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			1600	V
I_R	*reverse current*	V_R = 1600 V	T_{VJ} = 25°C			100	µA
		V_R = 1600 V	T_{VJ} = 125°C			2	mA
V_F	*forward voltage drop*	I_F = 60 A	T_{VJ} = 25°C			1.16	V
		I_F = 180 A				1.55	V
		I_F = 60 A	T_{VJ} = 125 °C			1.09	V
		I_F = 180 A				1.59	V
I_{DAV}	*bridge output current*	T_C = 90°C rectangular d = ⅓	T_{VJ} = 150°C			180	A
V_{F0}	*threshold voltage*	*for power loss calculation only*	T_{VJ} = 150°C			0.81	V
r_F	*slope resistance*					4.4	mΩ
R_{thJC}	*thermal resistance junction to case*					0.6	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.2		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			205	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			1.10	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.19	kA
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			935	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.01	kA
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			6.05	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			5.89	kA²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			4.37	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			4.25	kA²s
C_J	*junction capacitance*	V_R = 400 V; f = 1 MHz	T_{VJ} = 25°C		37		pF

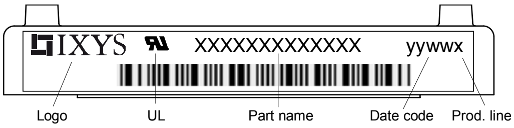
Brake IGBT

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient gate emitter voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			155	A
I_{C80}			T_C = 80°C			108	A
P_{tot}	*total power dissipation*		T_C = 25°C			500	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 100 A; V_{GE} = 15 V	T_{VJ} = 25°C		2.05	2.35	V
			T_{VJ} = 125°C		2.45		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 4 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5.4	5.9	6.5	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.1	mA
			T_{VJ} = 125°C		0.1		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				500	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 100 A			295		nC
$t_{d(on)}$	*turn-on delay time*	inductive load	T_{VJ} = 125°C		70		ns
t_r	*current rise time*	V_{CE} = 600 V; I_C = 100 A			40		ns
$t_{d(off)}$	*turn-off delay time*	V_{GE} = ±15 V; R_G = 6.8 Ω			250		ns
t_f	*current fall time*				100		ns
E_{on}	*turn-on energy per pulse*				8.5		mJ
E_{off}	*turn-off energy per pulse*				11.5		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 6.8 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEK} = 1200 V				300	A
SCSOA	*short circuit safe operating area*						
t_{SC}	*short circuit duration*	V_{CE} = 720 V; V_{GE} = ±15 V	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 6.8 Ω; non-repetitive			400		A
R_{thJC}	*thermal resistance junction to case*					0.25	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.10		K/W

Brake Diode

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RRM}	*max. repetitive reverse voltage*		T_{VJ} = 25°C			1200	V
I_{F25}	*forward current*		T_C = 25°C			48	A
I_{F80}			T_C = 80°C			32	A
V_F	*forward voltage*	I_F = 30 A	T_{VJ} = 25°C			2.75	V
			T_{VJ} = 125°C		1.80		V
I_R	*reverse current*	V_R = V_{RRM}	T_{VJ} = 25°C			0.25	mA
			T_{VJ} = 125°C			1	mA
Q_{rr}	*reverse recovery charge*	V_R = 600 V			1.8		µC
I_{RM}	*max. reverse recovery current*	$-di_F/dt$ = 400 A/µs	T_{VJ} = 125°C		23		A
t_{rr}	*reverse recovery time*	I_F = 30 A			150		ns
R_{thJC}	*thermal resistance junction to case*					0.9	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.3		K/W

Package V2-Pack			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal			100	A
T_{stg}	*storage temperature*		-40		125	°C
T_{VJ}	*virtual junction temperature*		-40		150	°C
Weight				76		g
M_D	*mounting torque*		2		2.5	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*	*terminal to terminal*	6.0			mm
$d_{Spb/Apb}$		*terminal to backside*	12.0			mm
V_{ISOL}	*isolation voltage*	t = 1 second; 50/60 Hz, RMS; $I_{ISOL} \le 1$ mA	3600			V
		t = 1 minute	3000			V

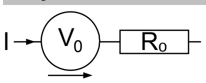


Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUB120-16NOX	VUB120-16NOX	Box	6	510468

Similar Part	Package	Voltage class
VUB120-16NOXT	V2-Pack	1600

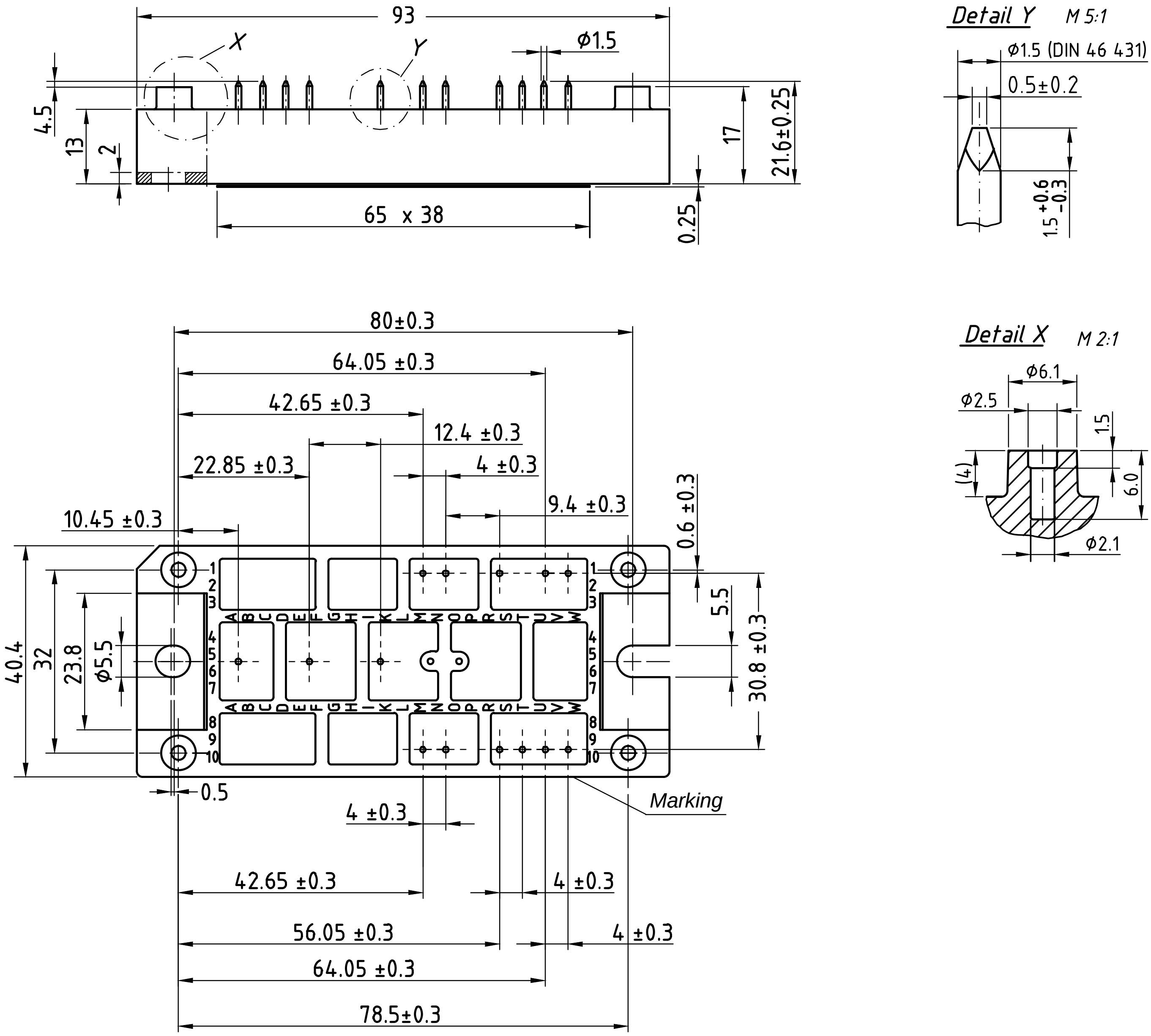
Equivalent Circuits for Simulation

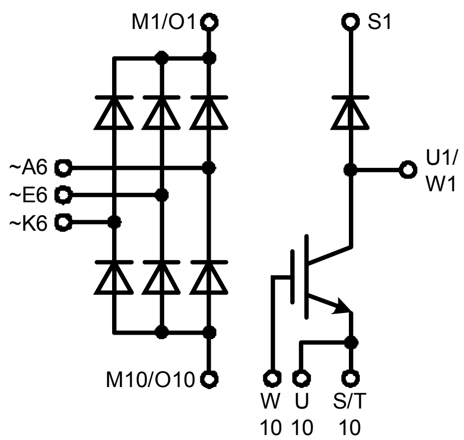
** on die level* $T_{VJ} = 150\,°C$



		Rectifier	Brake IGBT	Brake Diode	
$V_{0\,max}$	*threshold voltage*	0.81	1.1	1.31	V
$R_{0\,max}$	*slope resistance **	3.2	13.8	8	mΩ

Outlines V2-Pack





Rectifier

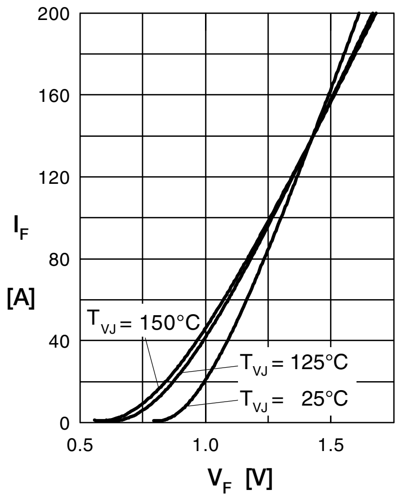


Fig. 1 Forward current vs. voltage drop per diode

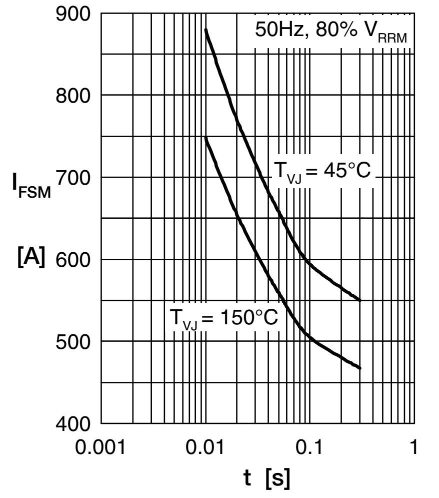


Fig. 2 Surge overload current vs. time per diode

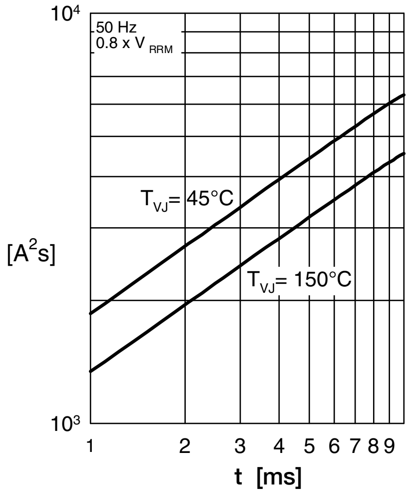


Fig. 3 I^2t vs. time per diode

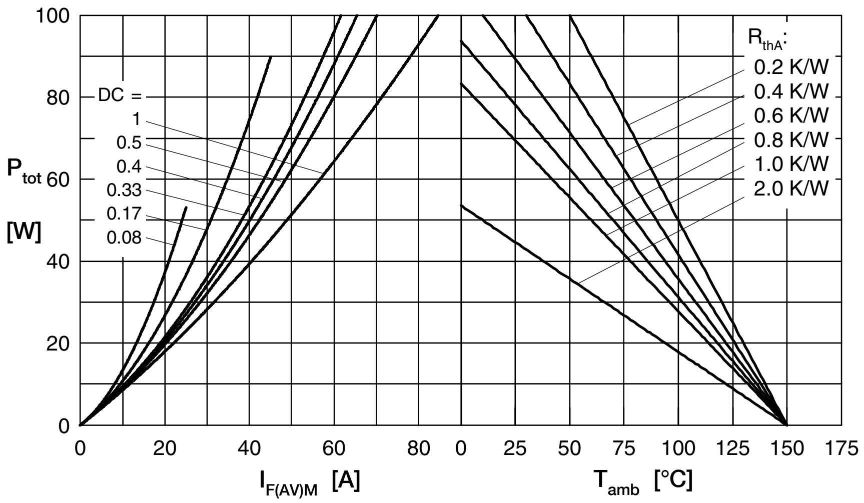


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

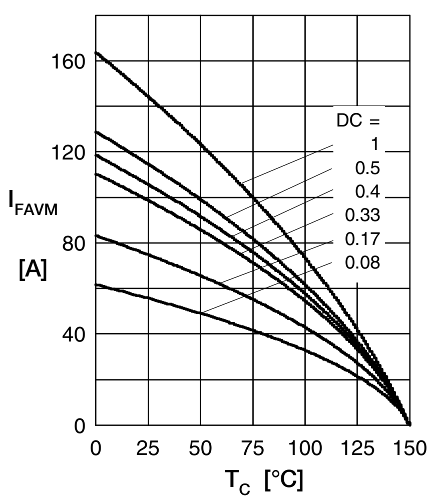


Fig. 5 Max. forward current vs. case temperature per diode

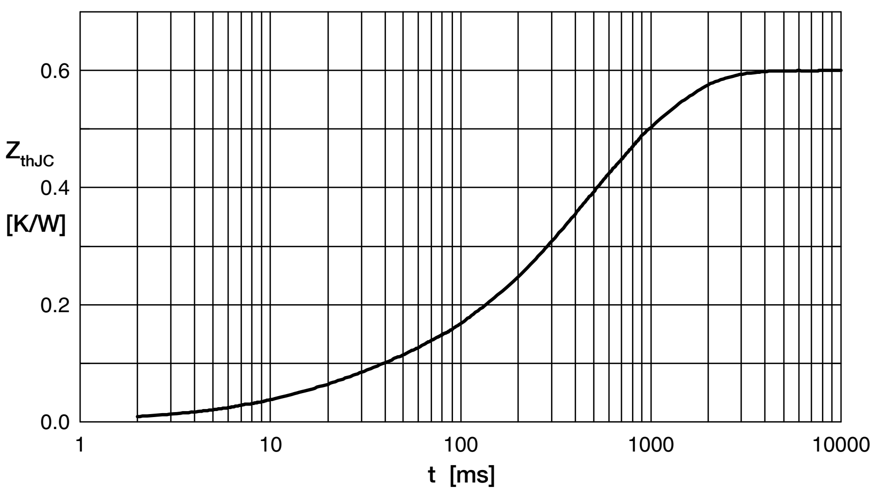


Fig. 6 Transient thermal impedance junction to case vs. time per diode

R_i	t_i
0.060	0.020
0.003	0.010
0.150	0.225
0.243	0.800
0.144	0.580

Brake IGBT

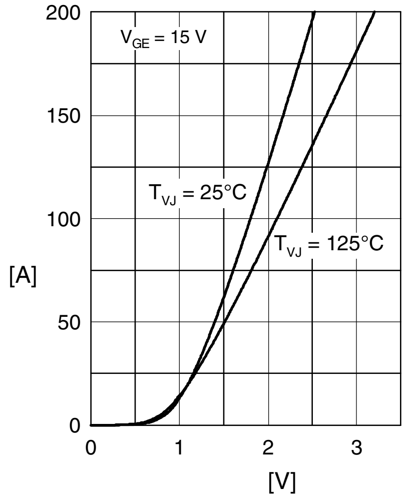


Fig. 1 Typ. output characteristics

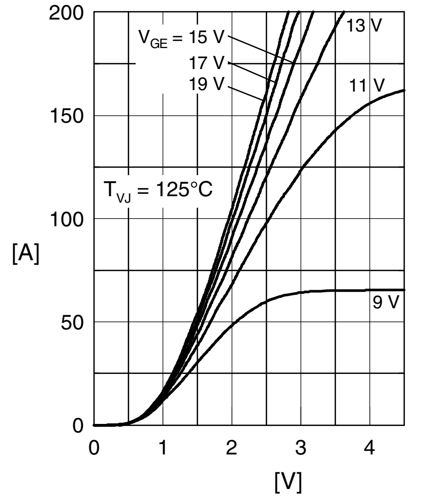


Fig. 2 Typ. output characteristics

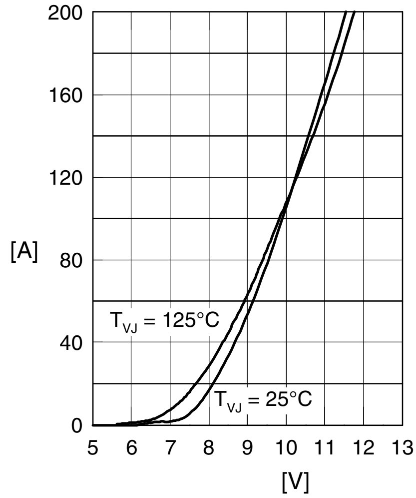


Fig. 3 Typ. transfer characteristics

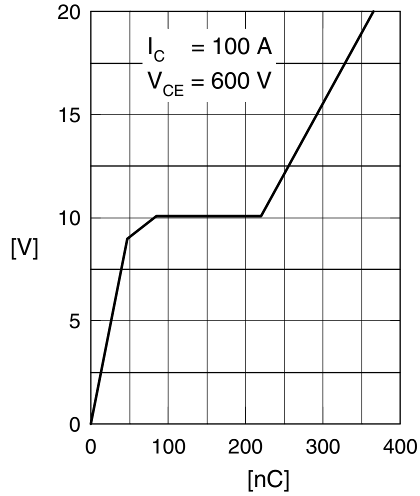


Fig. 4 Typ. turn-on gate charge

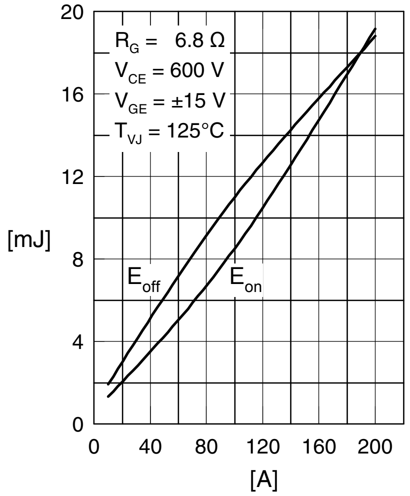


Fig. 5 Typ. switching energy versus collector current

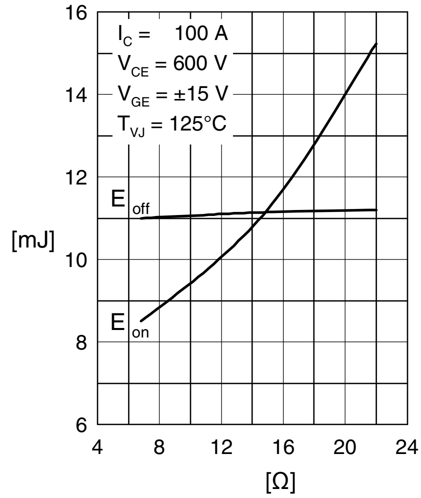


Fig. 6 Typ. switching energy versus gate resistance

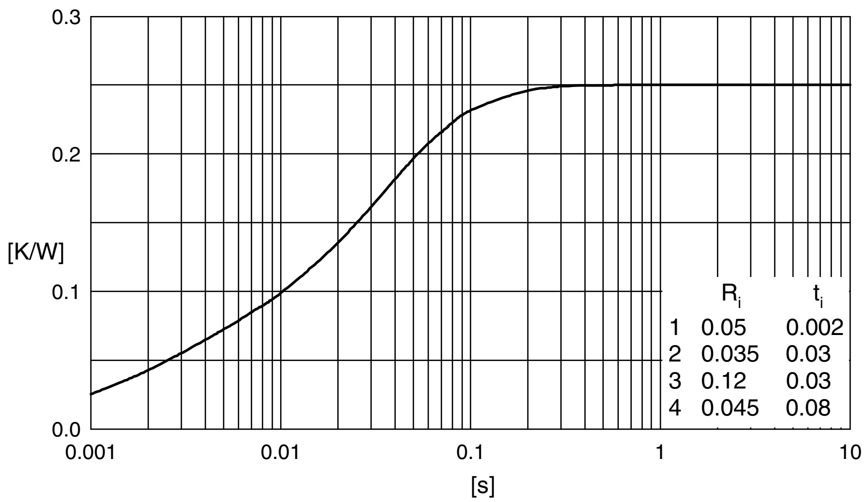


Fig. 7 Transient thermal impedance junction to case

Brake Diode

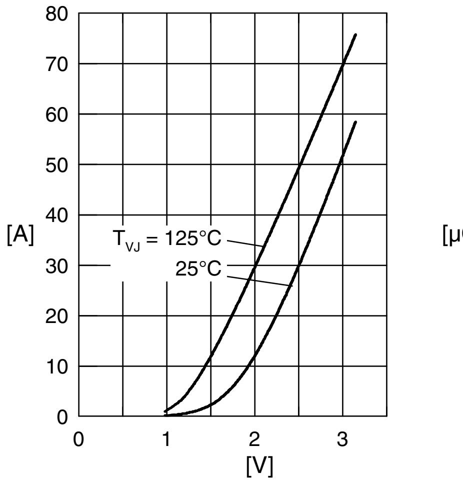


Fig. 1 Typ. forward current I_F vs. V_F

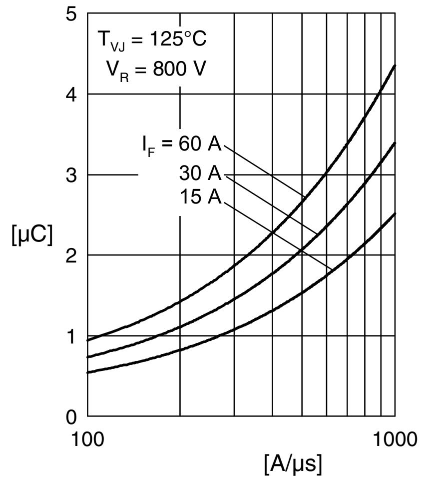


Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

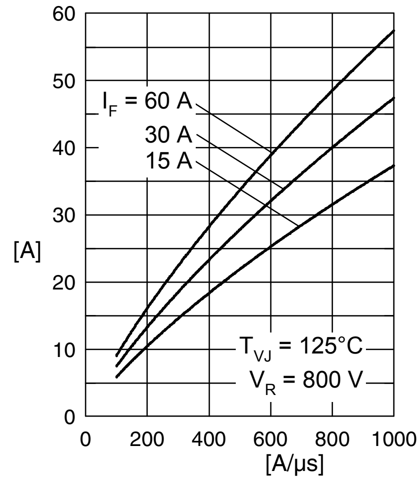


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

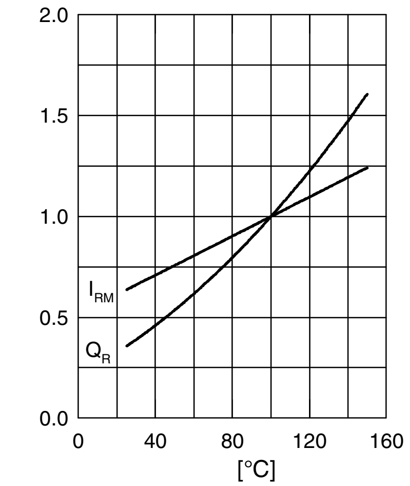


Fig. 4 Typ. dynamic parameters Q_r, I_{RM}, versus T_{VJ}

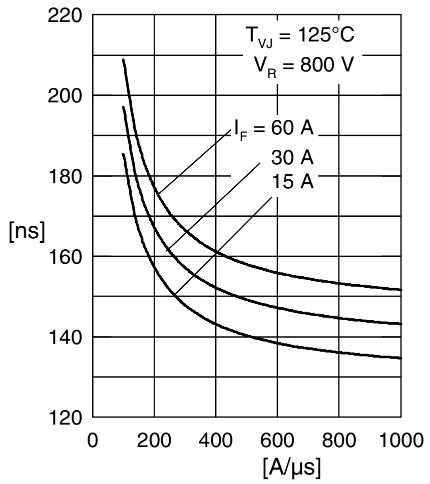


Fig. 5 Typ. recovery time t_{rr} vs. $-di_F/dt$

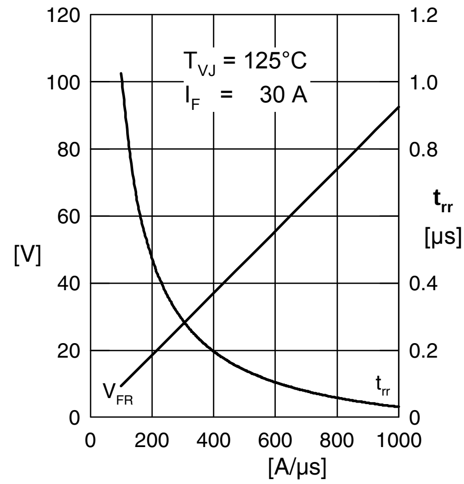
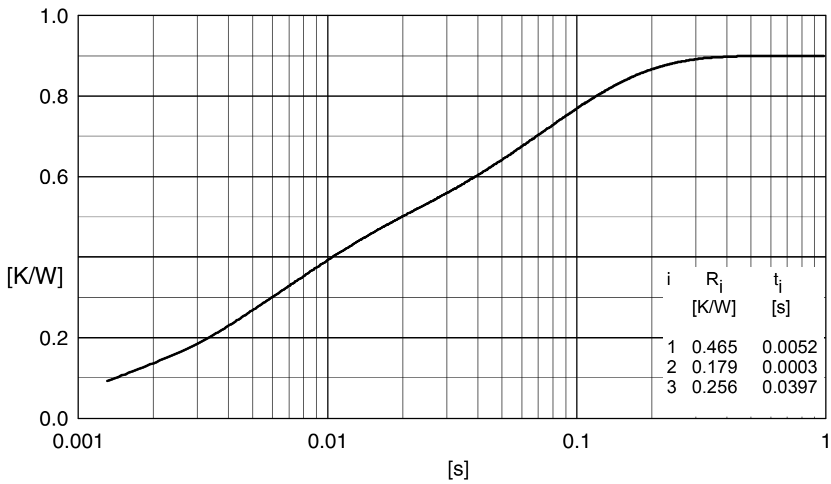


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt



i	R_i [K/W]	t_i [s]
1	0.465	0.0052
2	0.179	0.0003
3	0.256	0.0397

Fig. 7 Typ. transient thermal impedance junction to case